

20-3650

ONE TO ONE RATIO

EPOXY POTTING AND ENCAPSULATING COMPOUND

DESCRIPTION:

20-3650 is an easy to use, one to one ratio, electronic grade epoxy potting, casting, and encapsulating system. This system exhibits excellent physical, thermal, and electrical insulation properties. 20-3650 is D.O.T. non-hazardous, easy to mix, and will cure at room temperature or with mild heat.

20-3650 is low in viscosity and ideal for meter mix and dispense equipment.

TYPICAL SPECIFICATIONS:

Color	
Resin	Black
Catalyst	White
Mixed	Dark Grey
Viscosity, 25°C cps	
Resin	25,000
Catalyst	12,000
Specific Gravity, 25°C	
Resin	1.5
Catalyst	1.5
Mix Ratio, by weight & volume	1:1
Pot Life, 100 grams, 25 °C	60 Minutes
Hardness, Shore D	75
Tensile Strength, psi	11,000
Compressive Strength, psi	15,500
Linear Shrinkage, in/in	0.004
Thermal Conductivity, BTU/hr/ft ² /°F/in.	4.2
Thermal Expansion Coefficient, /°C	27 x 10 ⁻⁶
Operating Temp. Range, °C	-60 to +150
Dielectric Strength, Volts/Mil	460
Dielectric Constant at 60 HZ	4.3
Dissipation Factor, 60 HZ	0.02
Volume Resistivity, OHM-CM	2.1 x 10 ¹⁵



INSTRUCTIONS FOR USE:

Some settling of fillers is common during transportation and storage. Remix individual components before using.

By weight or volume mix equal parts 20-3650 Resin and Catalyst. Mix thoroughly being careful not to introduce excessive air into the mixture.

Pour and allow material to cure according to one of the following schedules:

24 hours at 25 °C/77°F

1 hour at 65 °C/150°F

15 minutes at 100 °C/212°F

IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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